

PMP11612 REV A Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
C2	1	2200pF	GCM155R71H222KA37D	MuRata	CAP, CERM, 2200 pF, 50 V, +/- 10%, X7R, AEC-Q200 Grade 1, 0402	0402
C3	1	470pF	VJ1206Y471KXEAT5Z	Vishay-Dale	CAP, CERM, 470 pF, 500 V, +/- 10%, X7R, 1206	1206
C4, C5	2	10uF	UVC2G100MPD1TD	Nichicon	CAP, AL, 10 µF, 400 V, +/- 20%, 18 ohm, TH	D10xL20mm
C6, C7	2	680uF	6SEPC680MW	Panasonic	CAP, AL, 680 µF, 10 V, +/- 20%, 0.007 ohm, TH	D10x12.5mm
C8	1	100pF	DE1B3KX101KB4BN01F	MuRata	CAP CER 100PF 250V RADIAL	
F1	1	1A	0263001.WRT1L	Littelfuse	Fuse, 1 A, 250VAC/VDC, TH	
C9	1	2.2uF	C2012X7R1H225K125AC	TDK	CAP, CERM, 2.2 µF, 50 V, +/- 10%, X7R, 0805	0805
C10	1	0.47uF	GRM188R61A474KA61D	MuRata	CAP, CERM, 0.47 µF, 10 V, +/- 10%, X5R, 0603	0603
D2	1	50V	SBRT15U50SP5-13	Diodes Inc.	Diode, Super Barrier Rectifier, 50 V, 15 A, AEC-Q101, PowerDI5	PowerDI5
D3, D5, D6, D7, D8	5	600V	DFLR1600-7	Diodes Inc.	Diode, Standard Recovery Rectifier, 600 V, 1 A, PowerDI123	PowerDI123
D4	1	200V	BAS20HT1G	ON Semiconductor	Diode, Switching, 200 V, 0.2 A, AEC-Q101, SOD-323	SOD-323
J1	1			Mill-Max	Connector, Receptacle, USB TYPE A, R/A, Top Mount SMT	USB TYPE A CONNECTOR RECEPTACLE 4POS SMD
L1	1	220u	7447462221	Würth	Inductor, Unshielded Drum Core, Ferrite, 220 µH, 0.5 A, 0.96 ohm, TH	D6 x 8.5mm
Q1	1	650V	SW7N65K	Samwin	MOSFET, N-CH, 600 V, 7 A, IPAK	IPAK
R5	1	10.0k	CRCW080510K0FKEA	Vishay-Dale	RES, 10.0 k, 1%, 0.125 W, 0805	0805
R6	1	20.0	CRCW080520R0FKEA	Vishay-Dale	RES, 20.0, 1%, 0.125 W, 0805	0805
R7, R14	2	4.7Meg	CRCW08054M70JNEA	Vishay-Dale	RES, 4.7 M, 5%, 0.125 W, 0805	0805
R8	1	470k	RC1206FR-07470KL	Yageo America	RES, 470 k, 1%, 0.25 W, 1206	1206
R10, R12, R30	3	620	RC1206FR-07620RL	Yageo America	RES, 620, 1%, 0.25 W, 1206	1206
R13	1	1.30k	RC0603FR-071K3L	Yageo America	RES, 1.30 k, 1%, 0.1 W, 0603	0603
R16	1	2.2Meg	CRCW08052M20JNEA	Vishay-Dale	RES, 2.2 M, 5%, 0.125 W, 0805	0805
R17	1	10.0	RC0603FR-0710RL	Yageo America	RES, 10.0, 1%, 0.1 W, 0603	0603
R18	1	47	CRCW060347R0JNEA	Vishay-Dale	RES, 47, 5%, 0.1 W, 0603	0603
R19	1	68.0k	RC0603FR-0768KL	Yageo America	RES, 68.0 k, 1%, 0.1 W, 0603	0603
R20	1	620k	RC0603FR-07620KL	Yageo America	RES, 620 k, 1%, 0.1 W, 0603	0603
R21	1	1.80k	RC0603FR-071K8L	Yageo America	RES, 1.80 k, 1%, 0.1 W, 0603	0603
R22	1	2.00	RC0805FR-072RL	Yageo America	RES, 2.00, 1%, 0.125 W, 0805	0805
R23	1	2.4	RC0805FR-072R4L	Yageo America	RES, 2.4, 1%, 0.125 W, 0805	0805
R24	1	43.0k	RC0603FR-0743KL	Yageo America	RES, 43.0 k, 1%, 0.1 W, 0603	0603
R26	1	0	RC0805JR-070RL	Yageo America	RES, 0, 5%, 0.125 W, 0805	0805
RT1	1	4.7	B57153S479M51	TDK	ICL 4.7 OHM 20% 3A 8.5MM	
T1	1	850uH	10339-T048	Sumida	Transformer, Flyback, EE16	
U1	1	UCC28704	UCC28704DBVR-1	Texas Instruments	IC, Constant Voltage, Constant Current PWM With Primary Side Regulation	

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